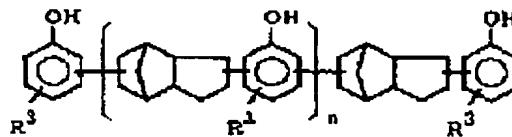


## EUROPEAN PATENT OFFICE

## Patent Abstracts of Japan

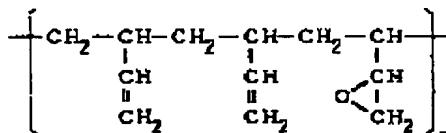
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I

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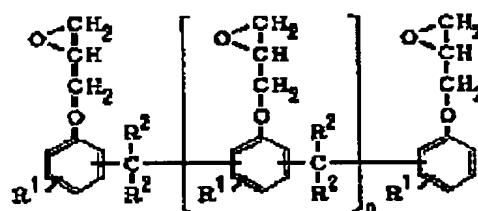
APPLICANT : TOSHIBA CHEM CORP;



II

INT.CL. : C08G 59/34 C08G 59/18 C08G 59/62  
 C08K 3/00 C08L 63/00 H01L 23/29  
 H01L 23/31

TITLE : PRODUCTION OF EPOXY RESIN  
 COMPOSITION AND  
 SEMICONDUCTOR-SEALING DEVICE



III

ABSTRACT : PURPOSE: To obtain an epoxy resin composition excellent in resistance to reflow cracking after moisture absorption with heat and moisture vapor by dispersing a specific epoxide in a specific phenolic resin and allowing them to react with each other under heating, then heat-kneading the product together with an epoxy resin and an inorganic filler as main starting substances with heat.

CONSTITUTION: In the presence of (A) a hardening accelerator such as an organic phosphine or a tertiary amine, (B) preferably a dicyclopentadiene- phenolic resin of formula I (R<sup>3</sup> is H, methyl; n is 0 or an integer of 1-5) and (C) an epoxy-containing polybutadiene are dispersed, as they are heated to effect their reactions. Then, the resin composition thus obtained is combined with (D) an epoxy resin of formula III (R<sup>1</sup> is H, a halogen, an alkyl; R<sup>2</sup> is H, an alkyl; n is an integer of 1 or more) and (E) an inorganic filler in an amount of 70-90wt.% in total and kneaded with heat to give the objective composition.

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